



Material Content Data Sheet



Sales Product Name	TLE7734G			Issued	19. January 2018			
MA#	MA001621228							
Package	PG-DSO-52-4			Weight*	869.08 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.200	1.98	1.98	19791	19791
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		84	
	non noble metal	zinc	7440-66-6	0.293	0.03		337	
	non noble metal	iron	7439-89-6	5.854	0.67		6736	
wire	non noble metal	copper	7440-50-8	237.701	27.35	28.06	273508	280665
	noble metal	gold	7440-57-5	2.311	0.27	0.27	2659	2659
	encapsulation	organic material	carbon black	1333-86-4	1.183	0.14		1361
encapsulation	plastics	epoxy resin	-	54.413	6.26		62610	
	inorganic material	silicondioxide	60676-86-0	535.854	61.65	68.05	616573	680544
leadfinish	non noble metal	tin	7440-31-5	7.508	0.86	0.86	8639	8639
plating	noble metal	silver	7440-22-4	0.935	0.11	0.11	1075	1075
glue	plastics	epoxy resin	-	1.440	0.17		1657	
	noble metal	silver	7440-22-4	4.319	0.50	0.67	4970	6627
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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